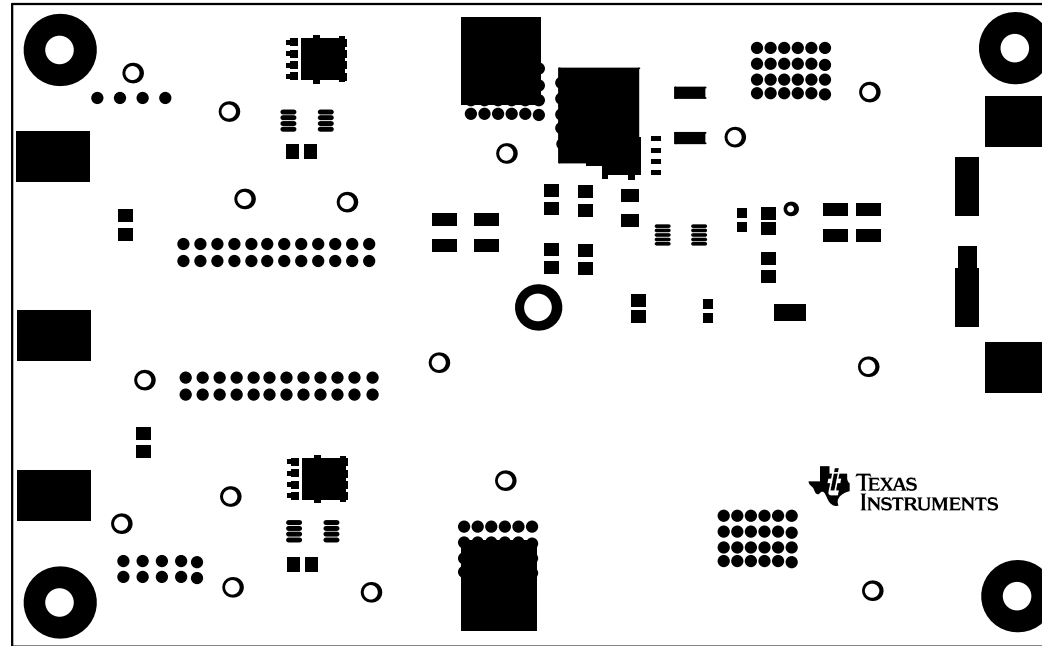
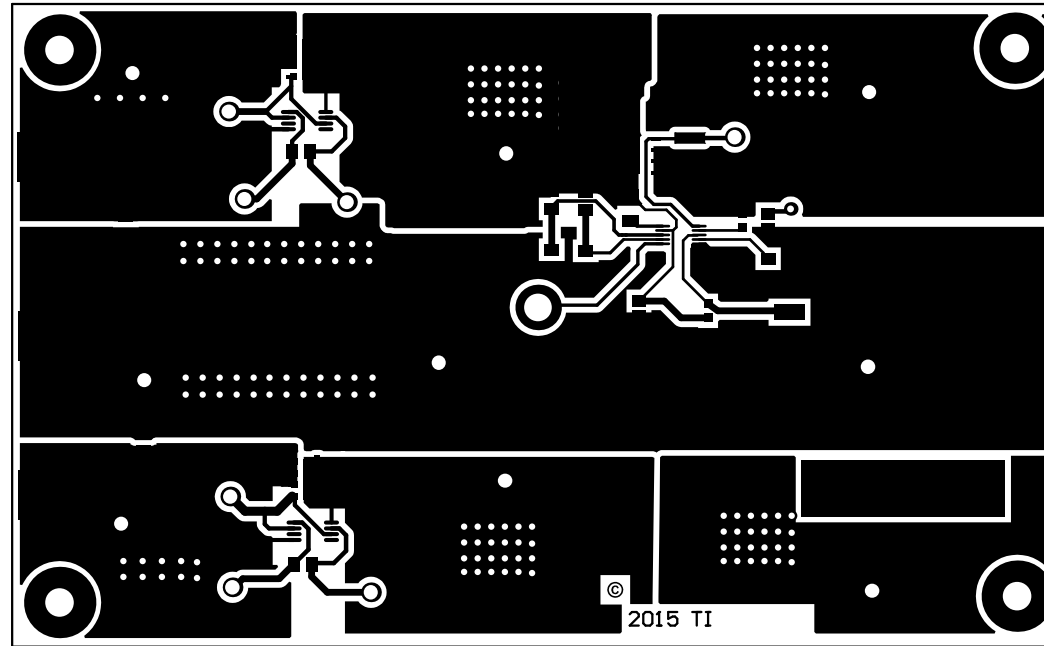


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/17/2015 6:38:31 PM	TEXAS INSTRUMENTS	

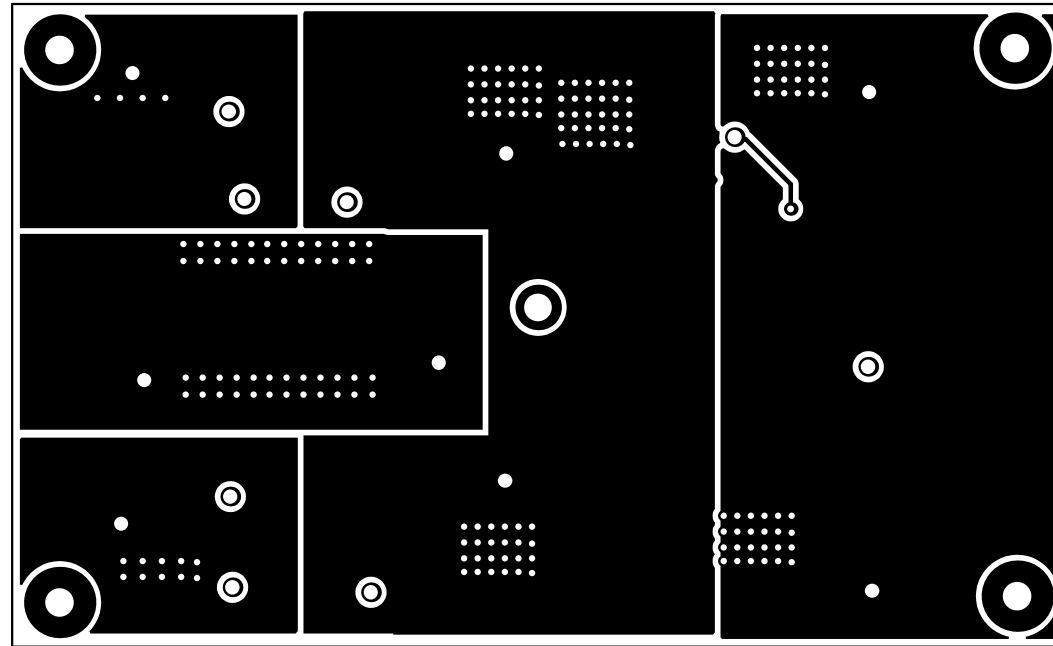


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/17/2015 6:38:32 PM	TEXAS INSTRUMENTS	

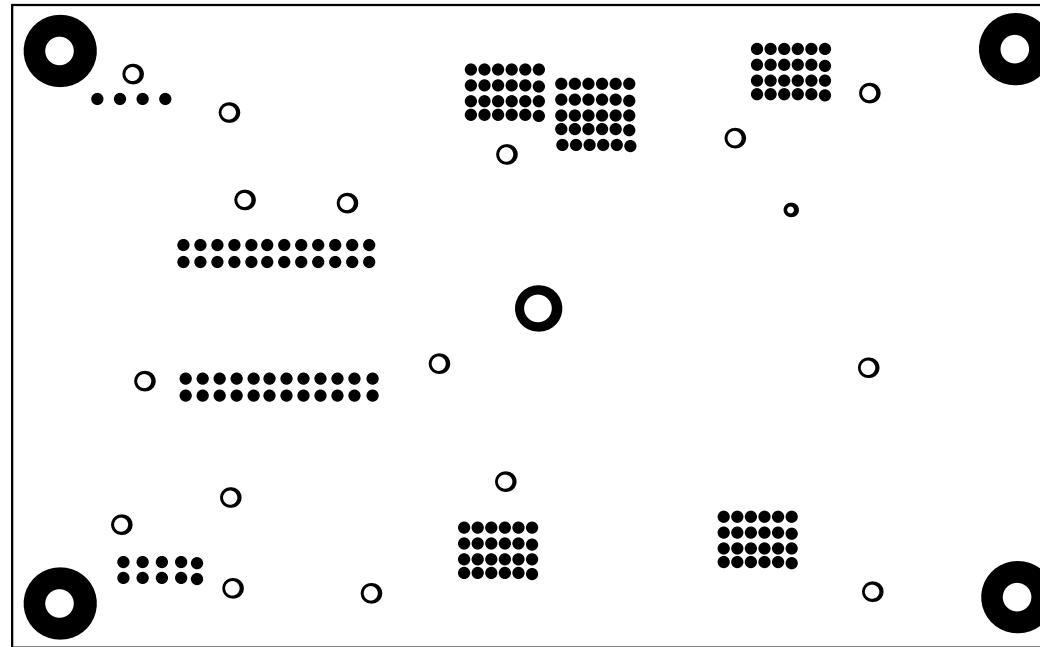


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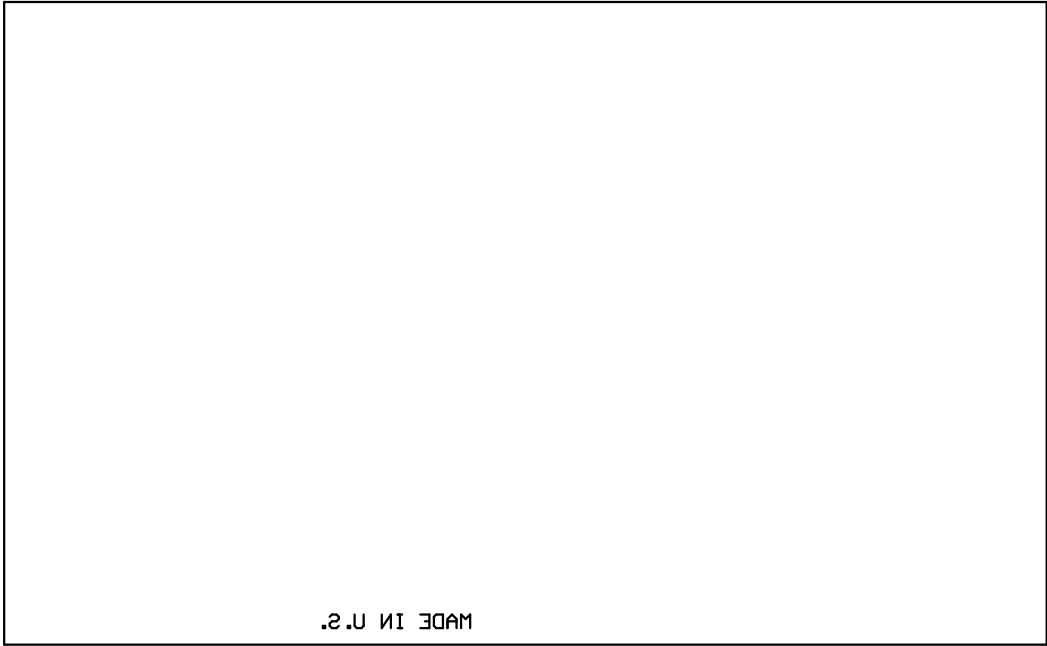
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/17/2015 6:38:33 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/17/2015 6:38:33 PM	TEXAS INSTRUMENTS	

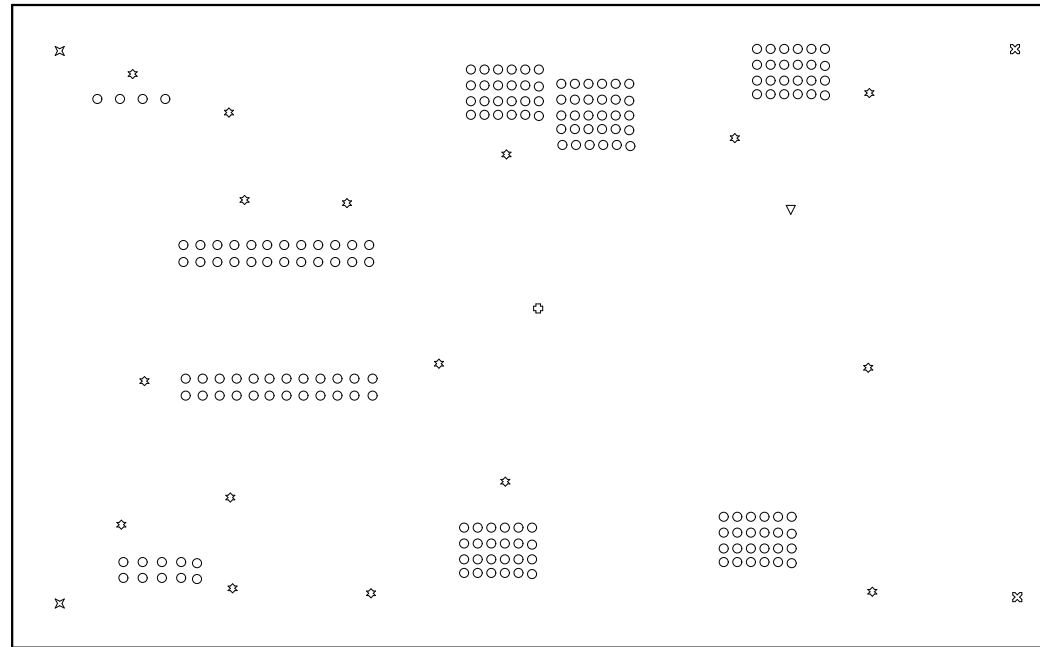


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/17/2015 6:38:34 PM	TEXAS INSTRUMENTS	

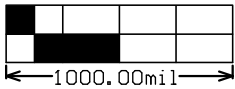
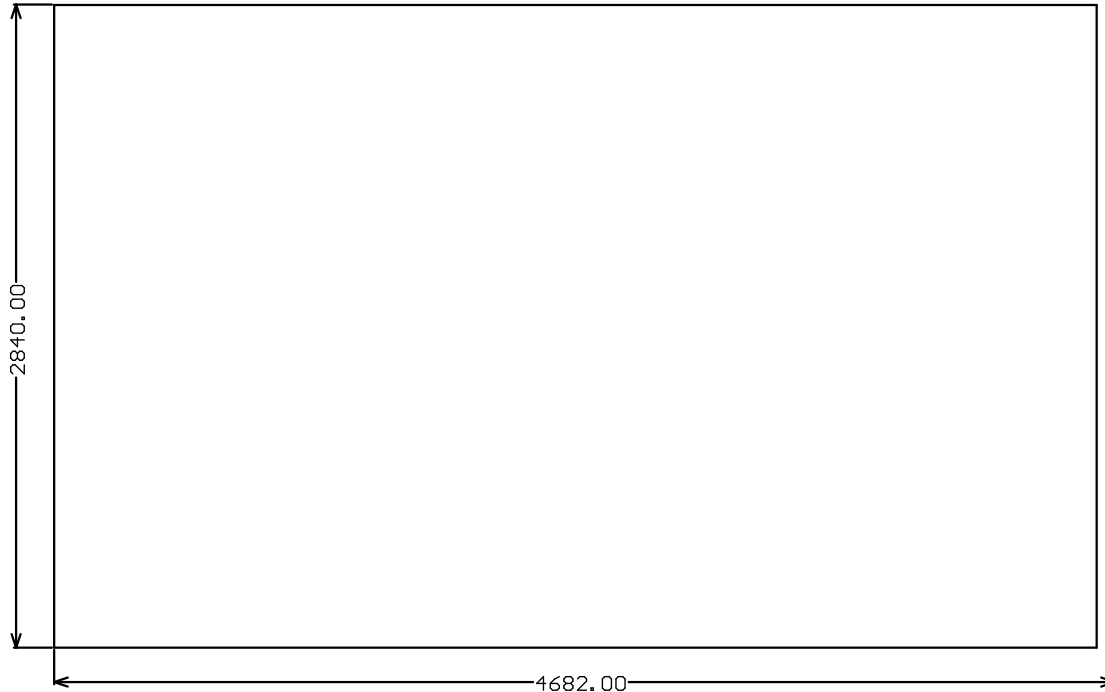


MADE IN U.S.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/17/2015 6:38:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/17/2015 6:38:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10748	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/17/2015 6:38:36 PM	TEXAS INSTRUMENTS	

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